Reg. No.						
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Question Paper Code

12568

B.E. / B.Tech. - DEGREE EXAMINATIONS, APRIL / MAY 2024

Eighth Semester

Electronics and Communication Engineering 20ECEL804 - EMBEDDED PRODUCT DEVELOPMENT

Regulations - 2020

Duration: 3 Hours Max				. Marks: 100				
	PART - A $(10 \times 2 = 20 \text{ Marks})$ Answer ALL Questions				Marks K- CO			
1.								
2.	2. Define a product development organization.							
3.	3. Show the physical decomposition of a bicycle.				CO2			
4.	4. What are latent needs?				CO2			
5.	5. Define delayed differentiation.				CO3			
6.	6. List any four motives for product change.				CO3			
7.	7. What is software recode?				CO4			
8.	8. What is CAD? Give some examples.				CO4			
9.	9. List various PCB documents.				CO5			
10.	10. What is the difference between single, double and multi-layer PCBs?				CO5			
PART - B ($5 \times 13 = 65$ Marks) Answer ALL Questions								
11.	a)	Explain the phases of generic product development process and point out the tasks and responsibilities of the organization. OR	13	K2 (CO1			
	b)	Explain the steps involved in product planning process.	13	K2 (CO1			
12.	a)	Elaborate the process of concept screening and concept scoring. OR	13	K2 (CO2			
	b)	Discuss on how behavior analysis on both customer and competitor is done.	13	K2 (CO2			
13.	a)	Explain the four-step method for establishing the product architecture. OR	13	K2 (CO3			
	b)	Explain the principles of prototyping in detail.	13	K2 (CO3			
14.	a)	Explain the need for CAE/CAD/CAM in Industrial design, using suitable illustrations.	13	K2 (CO4			

OR

b) Explain the basics of reverse engineering and its strategies in detail. 13 K2 CO4

15. a) Explain Grounding and Noise elimination methods in detail with ¹³ K2 CO5 diagrams.

OR

b) Explain any two embedded product modeling techniques in detail. 13 K2 CO5

PART - C $(1 \times 15 = 15 \text{ Marks})$

16. a) Explain the various translation and debugging tools used in Embedded 15 K2 CO6 product design.

OR

b) Explain the criteria in selection of Processors and Memories in ¹⁵ K2 CO6 Embedded Products Design.